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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/787,380	02/26/2004	Brad L. Grande	2-1	4270
47386 7590 03/30/2011 RYAN, MASON & LEWIS, LLP 1300 POST ROAD SUITE 205 FAIRFIELD, CT 06824				
EXAMINER				
GETACHEW, ABYY				
ART UNIT		PAPER NUMBER		
2835				
MAIL DATE		DELIVERY MODE		
03/30/2011		PAPER		

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

### Office Action Summary

**Application No.**

10/787,380

**Applicant(s)**

GRANDE ET AL.

**Examiner**

ABIY GETACHEW

**Art Unit**

2835

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 3/16/2011.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1-20 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-20 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 26 February 2004 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-848)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_

**DETAILED ACTION**

***Claim Rejections - 35 USC § 102***

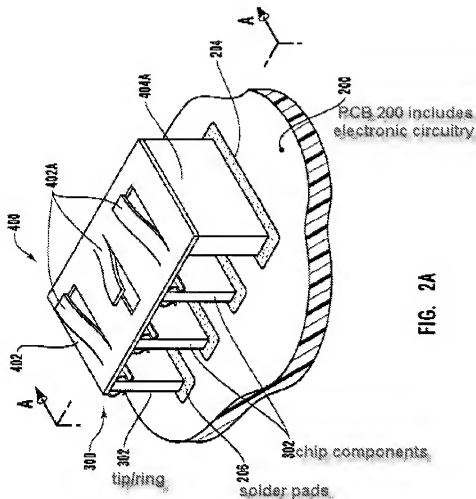
1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

2. Claims 1-20 are rejected under 35 U.S.C. 102(b) as being anticipated by Giles et al. (US 2002/0118517 A1) hereinafter refer as to Giles.

Regarding claims 1, Giles discloses modem module (Column 4 paragraph 0041) for connecting to a carrier assembly, comprising: circuitry (paragraph 0027, the chip components are arranged so that their respective first terminal elements can be joined to electronic circuitry of a printed circuit board, further see paragraph 0042, PCB 200 includes electronic circuitry 202) for interfacing with a telephone line (paragraph 0014, the modem and the telephone line to which the modem is connected); and one or more solder pads (figure 2A element 206) for connecting said modem module (paragraph 0014) to said carrier assembly (figure 2A element 200).



Regarding claims 2, Giles further discloses a tip/ring connector (figure 2A element 302) for interfacing with said telephone line. (Paragraph 0030, i.e. chip component assembly serves to provide a common AC reference between a modem in the PC card and the telephone line to which the modem is connected).

Regarding claims 3, Giles further discloses a connection to a tip/ring connector. (Figure 2A element 302).

Regarding claims 4, Giles discloses wherein said carrier assembly is a motherboard. (As illustrated in figures 1-2C, i.e. PC card 100 includes a housing 102 having a top cover 102A and a bottom cover 102B which cooperate to define a space in which PCB 200 is disposed. PCB 200 includes electronic circuitry 202 that is in electrical communication with one or more ground pads 204 and one or more solder pads 206. Mounted to PCB 200 are one or more chip component assemblies 300).

Regarding claims 5, Giles discloses wherein said one or more solder pads (figure 2A element 206) are soldered to corresponding one or more solder pads on said carrier assembly (see figures 2A-2C).

Regarding claims 6, Giles discloses wherein said modem assembly is fabricated on a printed circuit board. (See figures 2-2C) .

Regarding claims 7, Giles discloses wherein said modem assembly is an integrated device. (As depicted in figure 2-2C, a microelectronic computer circuit incorporated into a chip or semiconductor; a whole system rather than a single component).

Regarding claim 8, Giles discloses method for fabricating a modem module for connection to a carrier assembly, comprising the steps of:  
providing circuitry (paragraph 0042, PCB 200 includes electronic circuitry 202) on a printed circuit board (figure 2A element 200) for interfacing with a telephone line (paragraph 0014, the modem and the telephone line to which the modem is connected);  
and providing one or more solder pads (figure 2A element 206) on said printed circuit board for connecting a signal line of said modem module to said carrier assembly.

(Paragraph 0027, the chip components are arranged so that their respective first terminal elements can be joined to electronic circuitry of a printed circuit board).

Regarding claims 9, Giles further discloses a tip/ring connector (figure 2A element 302) for interfacing with said telephone line. (Paragraph 0030, i.e. chip component assembly serves to provide a common AC reference between a modem in the PC card and the telephone line to which the modem is connected).

Regarding claims 10, Giles further discloses a connection to a tip/ring connector (figure 2A element 302).

Regarding claims 11, Giles discloses wherein said carrier assembly is a motherboard (As illustrated in figures 1-2C, i.e. PC card 100 includes a housing 102 having a top cover 102A and a bottom cover 102B which cooperate to define a space in which PCB 200 is disposed. PCB 200 includes electronic circuitry 202 that is in electrical communication with one or more ground pads 204 and one or more solder pads 206. Mounted to PCB 200 are one or more chip component assemblies 300).

Regarding claims 12, Giles discloses wherein said one or more solder pads (figures 2A element 206) are soldered to corresponding one or more solder pads on said carrier assembly (see figure 2A-2C).

Regarding claims 13, Giles discloses wherein said modem assembly is fabricated on a printed circuit board. (See figures 2A-2C).

Regarding claims 7, Giles discloses wherein said modem assembly is an integrated device. (Figure 6 and 7 illustrated a cable having a plurality of incoming tip

and ring telephone lines and also the figures show a whole system rather than a single component).

Regarding claim 14, Giles discloses a printed circuit board, comprising: modem circuitry for interfacing (paragraph 0027, the chip components are arranged so that their respective first terminal elements can be joined to electronic circuitry of a printed circuit board, further see paragraph 0042, PCB 200 includes electronic circuitry 202) with a telephone line (paragraph 0014, the modem and the telephone line to which the modem is connected); and one or more solder pads (figure 2A element 206) for connecting a signal line of said modem circuitry to a carrier assembly (see figures 2A-2C).

Regarding claims 15, Giles further discloses a tip/ring connector (figure 2A element 302) for interfacing with said telephone line. (Paragraph 0014, the modem and the telephone line to which the modem is connected)

Regarding claims 16, Giles further discloses a connection to a tip/ring connector. (Figure 2A element 302).

Regarding claims 17, Giles discloses wherein said carrier assembly is a motherboard. (As illustrated in figures 1-2C, i.e. PC card 100 includes a housing 102 having a top cover 102A and a bottom cover 102B which cooperate to define a space in which PCB 200 is disposed. PCB 200 includes electronic circuitry 202 that is in electrical communication with one or more ground pads 204 and one or more solder pads 206. Mounted to PCB 200 are one or more chip component assemblies 300).

Regarding claims 18, Giles discloses wherein said one or more solder pads (figures 2A element 206) are soldered to corresponding one or more solder pads on said carrier assembly (see figures 2—2C).

Regarding claims 19, Giles discloses wherein said modem assembly is fabricated on a printed circuit board. (See figures 2A-2C).

Regarding claims 20, Giles discloses wherein said modem assembly is an integrated device. (Figure 6 and 7 illustrated a cable having a plurality of incoming tip and ring telephone lines and also the figures show a whole system rather than a single component).

### ***Response to Arguments***

3. Applicant's arguments filed 03/16/2011 have been fully considered but they are not persuasive.

First argument "In one aspect of the present invention, a modem module is provided that may be attached to a motherboard and thereby eliminates the need to recertify the motherboard. Applicants note that the Examiner does not allege that Giles et al. discloses solder pads on the modem module, as variously required by each independent claim. The Examiner references the solder pads 206 in FIG. 2A, but these solder pads" are on the PCB (i.e., the "carrier assembly," using the terminology of the current claims"



In response to the above argument, Applicant attention respectfully directed figure 2A further more see section 0010 and 0011, which is the chip component is mounted so that the respective terminal elements contact corresponding solder pads on the PCB. The chip component can then be permanently joined to the PCB by attaching the respective terminal elements to the appropriate solder pads by soldering. Giles teaches (see paragraph 0041 further as depicted in figures 1 and 2A PC card may take any of a variety of forms including, but not limited to, a memory card, modem card, network card, or the like).

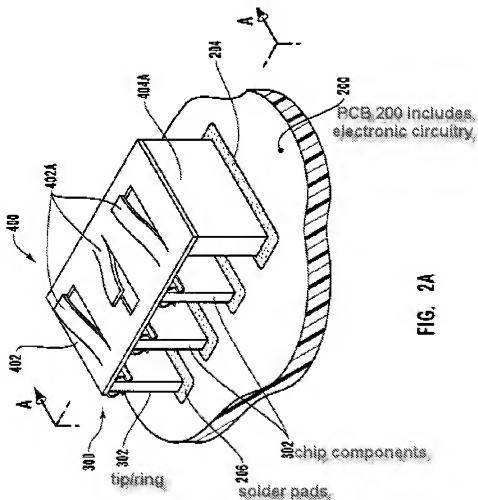


FIG. 2A

Second argument "Giles et al. do not disclose or suggest one or more solder pads for connecting a signal line of a modem module to a carrier assembly. Independent claims 1, 8, and 14 require one or more solder pads for connecting a signal line of said modem module to said carrier assembly.

In response to the above argument Giles et al. teaches that chip components are typically mounted on a printed circuit board (PCB) in a way that the lower surface is arranged in a face-down orientation with respect to the PCB, at least two of the rectangular side surfaces typically have attached thereto respective terminal elements suitable for connecting with corresponding solder pads on the PCB. The terminal elements, in turn, are in electrical communication with various functional elements contained within the chip component. Further, Applicant's attention respectfully directed to figure 2A and sections 0010 and 0011. Furthermore, as depicted in figure 2A, chip component assembly 300 includes a plurality of chip components 302 arranged so that each contacts a respective solder pad 206.

### ***Conclusion***

4. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to ABIY GETACHEW whose telephone number is (571)272-6932. The examiner can normally be reached on Monday to Friday 8Am to 4:30Pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Jinhee Lee can be reached on (571)272-1977. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Jinhee J Lee/  
Supervisory Patent Examiner, Art Unit 2835

Abiy Getachew  
Examiner  
Art Unit 2835

A.G.

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March 21, 2011